

IN THE CLAIMS

Please cancel claim 5.

Please amend the claims to read as indicated herein.

1.(currently amended) An optoelectronic device, comprising an open-ended metal canister, an insulating substrate, at least one optoelectronic component mounted on said substrate, and one or more electrical connections made to said component(s), wherein:

the insulating substrate closes the open end of the metal canister so that the metal canister and insulating substrate together form a housing for one or more of said components mounted on the substrate;

the insulating substrate acts as a circuit board to carry said electrical connections from said component(s) externally of the housing; and

the canister has at least one optical port by which optical radiation may be transmitted into and/or out of said housing; and

said electrical connection includes at least one via through said insulating substrate.

2. (previously presented) An optoelectronic device as claimed in Claim 1, in which the housing is hermetically sealed.

3. (previously presented) An optoelectronic device as claimed in Claim 1, wherein said optical port includes an optical window.

4. (previously presented) An optoelectronic device as claimed in Claim 1, wherein said optical port includes a receptacle for an optical component.

5. (canceled)

6. (currently amended) An optoelectronic device as claimed in Claim 51, in which said via extends to a side of the substrate opposite from a side of the substrate that closes the open end of the canister.

7. (previously presented) An optoelectronic device as claimed in Claim 6, wherein said electrical connection includes a track on or within said substrate that extends towards an edge of said substrate.

8. (previously presented) An optoelectronic device as claimed in claim 1, wherein said substrate includes a multilayer printed circuit board for making electrical connections internally and/or externally of said housing.

9. (previously presented) An optoelectronic device as claimed in claim 1, wherein said substrate includes a printed metallic layer to which the open end of the canister is bonded.

10. (previously presented) An optoelectronic device as claimed in claim 1, wherein said substrate is a ceramic substrate.

11. (previously presented) An optoelectronic device as claimed in Claim 1, wherein said substrate is a flex substrate.